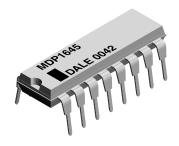
Vishay Dale

Thick Film Resistor Networks, Dual-In-Line, Molded DIP



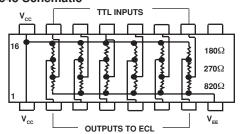
FEATURES

- · 0.190" [4.83mm] maximum seated height
- · Rugged, molded case construction
- Low temperature coefficient (- 55°C to + 125°C), MDP 1645: ± 100ppm/°C, MDP 1646: ± 250ppm/°C
- Compatible with automatic insertion equipment
- Highly stable thick film
- Reduces PC board space and reduces total assembly
- · Available in tube pack

STANDARD ELECTRICAL SPECIFICATIONS						
GLOBAL MODEL/ PIN NO.	RESISTOR POWER RATING Max. @ 70°C W	PACKAGE POWER RATING Max. @ 70°C W	STANDARD TOLERANCE ± %	TEMPERATURE COEFFICIENT (- 55°C to + 125°C) ppm/°C	TEMPERATURE COEFFICIENT TRACKING ppm/°C	WEIGHT g
MDP1645	0.125	2.0	2	± 100 Typical	± 150	1.5
MDP1646	0.125	2.0	5	± 250 Typical	± 150	1.5

CIRCUIT APPLICATIONS

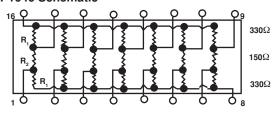
MDP1645 Schematic



TTL to ECL translator

The MDP1645 network consists of 18 resistors of 3 different values. internally divided into six (6) identical three (3) resistor sections for TTL to ECL translation.

MDP1646 Schematic



SCSI-BUS signal terminator

The MDP1646 network consists of 21 resistors of 2 different values, internally divided into seven (7) identical three (3) resistor sections for SCSI-BUS terminator applications.

GLOBAL PART NUMBER INFORMATION

New Global Part Numbering: MDP1646D04 (preferred part numbering format) M 6 4 SPECIAL **GLOBAL MODEL** PIN COUNT **SCHEMATIC PACKAGING** MDP **E04** = Lead Free, Tube **D04** = Tin/Lead, Tube 16 45 = TTL/ECL Translator Blank = Standard (Dash Number) 46 = Signal Terminator (up to 3 digits)
From **1-999** as applicable

Historical Part

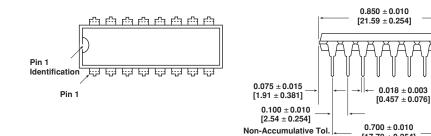
Number: MDP1646 (Will continue to be accepted)						
	MDP	16		46		D04
HIS	TORICAL MODEL	PIN COUNT		SCHEMATIC		PACKAGING

Thick Film Resistor Networks, Dual-In-Line, Molded DIP

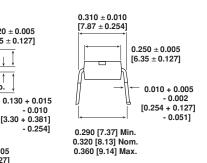
 $[17.78 \pm 0.254]$

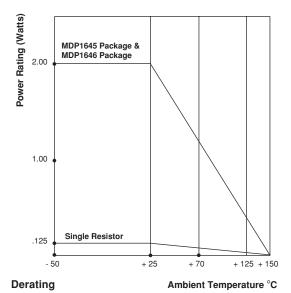
Vishay Dale

DIMENSIONS in inches [millimeters]



7 Spaces





TECHNICAL SPECIFICATIONS				
PARAMETER	UNIT	MDP Series		
Maximum Operating Voltage	VDC	100		
Voltage Coefficient of Resistance (Typical)	$V_{\rm eff}$	< 50 ppm/°C		
Operating Temperature Range	°C	- 55 to + 125		
Storage Temperature Range	°C	- 55 to + 150		

 0.120 ± 0.005 [3.05 \pm 0.127]

- 0.010 [3.30 + 0.381] - 0.254]

0.030 ↑ [0.762] Typ.

0.050 ± 0.005 [1.27 ± 0.127]

MECHANICAL SPECIFICATIONS				
Marking Resistance to Solvents:	Permanency testing per MIL- STD-202, Method 215.			
Solderability:	Per MIL-STD-202, Method 208E.			
Terminals:	Copper alloy, solder plated.			
Body:	Molded epoxy.			
Weight:	1.5 grams.			

PERFORMANCE				
TEST	CONDITIONS	MAX. ∆R (Typical Test Lots)		
Thermal Shock	5 cycles between - 65°C and + 125°C	± 0.50% ΔR		
Short Time Overload	2.5 x rated working voltage 5 seconds	± 0.25% ΔR		
Low Temperature Operation	45 minutes at full rated working voltage at - 65°C	± 0.25% ΔR		
Moisture Resistance	240 hours with humidity ranging from 80% RH to 98% RH	± 0.50% ΔR		
Resistance to Soldering Heat	Leads immersed in + 260°C solder to within 1/16" of body for 10 seconds	± 0.25% ΔR		
Shock	Total of 18 shocks at 100 g's	± 0.25% ΔR		
Vibration	12 hours at maximum of 20 g's between 10 and 2,000 Hz	± 0.25% ΔR		
Load Life	1,000 hours at + 70°C, rated power applied 1.5 hours "ON", 0.5 hour "OFF" for full 1000 hour period. Derated according to the curve.	± 0.50% ΔR		
Terminal Strength	4 1/2 pound pull for 30 seconds	± 0.25% ΔR		
Insulation Resistance	10,000 Megohm (minimum)	_		
Dielectric Withstanding Voltage	No evidence of arcing or damage (200 V RMS for 1 minute)	_		